



TO-263 物料成分表

Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition		CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English			
Die	14	Si		7440-21-3	100.00%
Lead Frame	823	CU		7440-50-8	99.37%
		Fe		7439-89-6	0.10%
		P		7723-14-0	0.33%
		Others		/	0.20%
Solder	16	Pb		7439-92-1	92.5%-95.5%
		Ag		7440-22-4	2.50%
		Sn		7440-31-5	2%-5%
Wire	8	CU		7440-50-8 231-159-6	99.00%
		Others		/	1.00%
		AL		7429-90-5	99.99%
		Others		7429-90-5	0.01%
Mold Compound	607	环氧树脂 A		商业秘密	3.00%
		环氧树脂 B		29690-82-2	3.00%
		酚醛树脂		商业秘密	3.00%
		二氧化硅(无定形)A		60676-86-0	87.50%
		二氧化硅(无定形)B		7631-86-9	3.00%
		炭黑		1333-86-4	0.50%
Plating	2	Tin		7440-31-5	≥99.99%
Total	1470				

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied. Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.